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 Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

logic symbol†

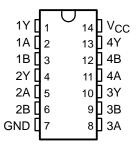
These devices contain four independent 2-input NOR gates. They perform the Boolean function $Y = \overline{A} + \overline{B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

The SN54HC02 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74HC02 is characterized for operation from -40°C to 85°C.

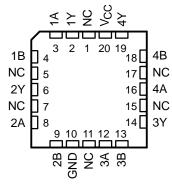
FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Y
Н	Χ	L
Χ	Н	L
L	L	н

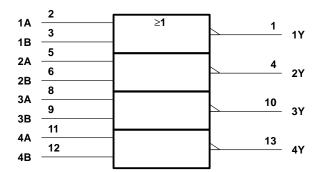
SN54HC02 . . . J OR W PACKAGE SN74HC02 . . . D, DB, N, OR PW PACKAGE (TOP VIEW)



SN54HC02 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC02, SN74HC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

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absolute maximum ratings over operating free-air temperature range†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, IIK (VI < 0 or VI > VCC) (se	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	127°C/W
•	DB package	158°C/W
	N package	78°C/W
	PW package	170°C/W
Storage temperature range, T _{Stg}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions

			s	SN54HC02			SN74HC02		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
V_{IH}	'IH High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
VIL		V _{CC} = 2 V	0		0.5	0		0.5	
	Low-level input voltage	V _{CC} = 4.5 V	0		1.35	0		1.35	V
		VCC = 6 V	0		1.8	0		1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	٧
		V _{CC} = 2 V	0		1000	0		1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V	0		500	0		500	ns
		V _{CC} = 6 V	0		400	0		400	
TA	Operating free-air temperature	_	-55		125	-40		85	°C



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		AMETER TEST CONDI		Vaa	Т	A = 25°C	;	SN54HC02		SN74HC02		UNIT
PARAMETER	1231 CC	NDITIONS V _{CC}		MIN	TYP	MAX	MIN	MAX	MIN	MAX	O.VIII		
			2 V	1.9	1.998		1.9		1.9		V		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4				
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9				
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84				
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34				
	VI = VIH or VIL	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V		
			4.5 V		0.001	0.1		0.1		0.1			
VOL			6 V		0.001	0.1		0.1		0.1			
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33			
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33			
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA		
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			2		40		20	μΑ		
C _i			2 V to 6 V		3	10		10		10	pF		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

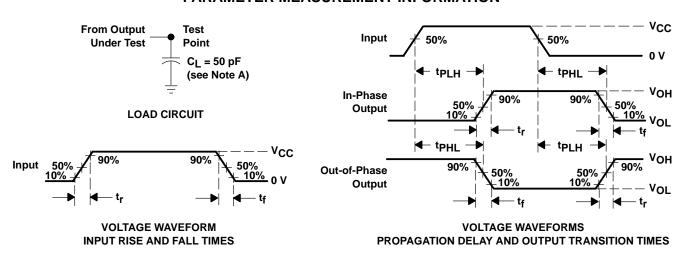
PARAMETER	METER FROM (INPUT) (O	PAMETER FROM TO VOC		Vaa	T _A = 25°C		SN54HC02		SN74HC02		UNIT
PARAMETER		(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A or B	Y	2 V		45	90		135		115	
t _{pd}			4.5 V		9	18		27		23	ns
			6 V		8	15		23		20	
	t _t Y		2 V		38	75		110		95	
t _t		Υ	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	No load	22	pF

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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